

## C0603X361M2TAC7411

**General Information** 

Series Style

Description

**Features** 

SMD Comm X8G HT150C Flex, Ceramic, 360 pF, 20%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603,  $0.4\,\mathrm{mm}$ 

SMD Comm X8G HT150C Flex

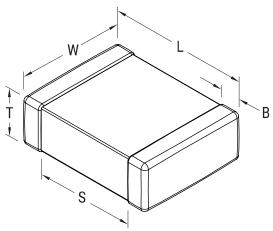
SMD, MLCC, High Temperature,

High Temperature, Ultra-Stable

SMD Chip

Ultra-Stable





		RoHS	Yes
		Termination	Flexible Termination
Click here for the 3D model.		Marking	No
		AEC-Q200	No
		Typical Component Weight	4.6 mg
		Shelf Life	78 Weeks
		MSL	1
Dimensions		Specifications	
Chip Size	0603	Capacitance	360 pF
L	1.6mm +/-0.17mm	Measurement Condition	1 MHz 1.0Vrms

Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

Specifications	
Capacitance	360 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	20%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 05/05/2025 © 2006 - 2025 YAGEO